

# Connector for CompactFlash™

SCFB Series



Unique eject mechanism achieves high operability and 5mm ejection stroke.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

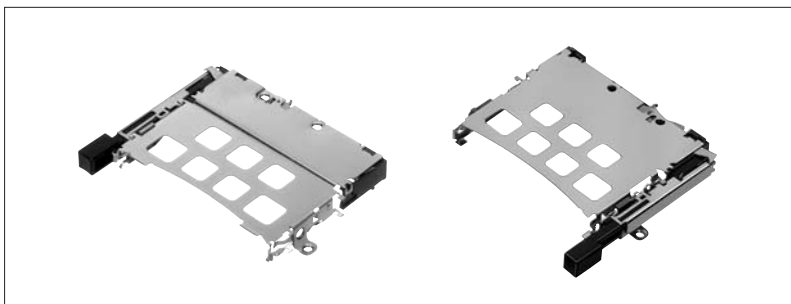
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



## Features

- Metal-plated structure enhances noise reduction and mechanical strength.
- Screw clamping structure strengthens mounting.
- Minimized depth design contributes to smaller body structure.

## Applications

- For digital still cameras, digital camcorders, various personal digital assistants and printers
- For flat panel TVs
- For notebook PCs

## Typical Specifications

Items		Specifications
		Type II compatible
Structure	Pin pitch	1.27mm
	Numbers of pins	50pins
	Applicable media	Type I , Type II
	Media ejection	5mm
	Mounting type	Surface mounting type
	Mounting style	Standard mount/Reverse mount
	Eject mechanism	2 step
	Stand-off	0/1.2mm
Performance	Operating temperature range	-20°C to +60°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Insertion and removal cycle	10,000cycles

**Product Line**

Media ejection structure	Mounting system	Stand-off (mm)	Position of knob	Applicable card	Product No.		Drawing No.
					Pin header	Ejector	
2 step lever ejection type	Standard mount	0	Right	Type I/Type II	SCFB1A0500	SCFB3A0300	1
			Left			SCFB3A0900	2
		1.2	Right		SCFB1A0900	SCFB3A0200	3
			Left		SCFB3A1000	4	
	Reverse mount	0	Right		SCFB1A0600	SCFB3A0400	5
			Left		SCFB3A0500	6	

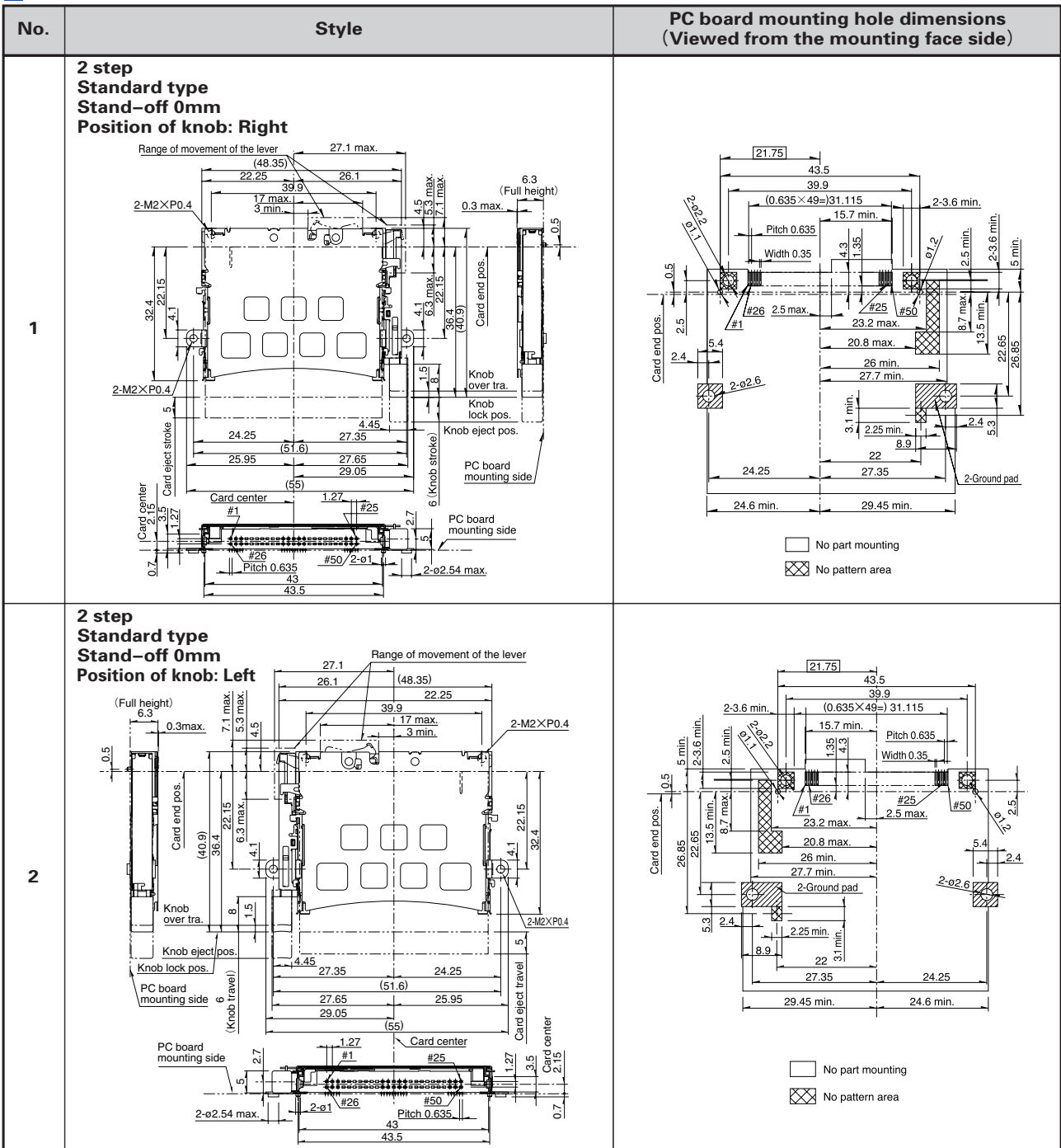
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**Note**

Pin headers and ejectors are supplied as separate parts. To apply these parts, solder the pin header to the printed circuit board, assemble the ejector to the pin header and screw clamp.

**Dimensions**

Unit:mm



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Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
<p>For SD Memory Card</p> <p>For microSD™ Card</p> <p>For SIM Card 8pins</p> <p>For W-SIM</p> <p>For Memory Stick Micro™</p> <p>For Memory Stick™</p> <p>Combine Type</p> <p>For Compact Flash™</p> <p>For PC cards supporting CardBus</p>	<p><b>2 step</b> <b>Standard type</b> <b>Stand-off 1.2mm</b> <b>Position of knob: Right</b></p>	<p> <input type="checkbox"/> Mounted part height 1.15 max.  <input checked="" type="checkbox"/> No part mounting         </p>
<p>For Express Card™</p> <p>For CMOS Camera Module</p>	<p><b>2 step</b> <b>Standard type</b> <b>Stand-off 1.2mm</b> <b>Position of knob: Left</b></p>	<p> <input type="checkbox"/> Mounted part height 1.15 max.  <input checked="" type="checkbox"/> No part mounting         </p>

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
5	<p><b>2 step Reverse type Stand-off 0mm Position of knob: Right</b></p>	<p> <input type="checkbox"/> No part mounting  <input checked="" type="checkbox"/> Land area  <input checked="" type="checkbox"/> No pattern area         </p>
6	<p><b>2 step Reverse type Stand-off 0mm Position of knob: Left</b></p>	<p> <input type="checkbox"/> No part mounting  <input checked="" type="checkbox"/> No pattern area         </p>

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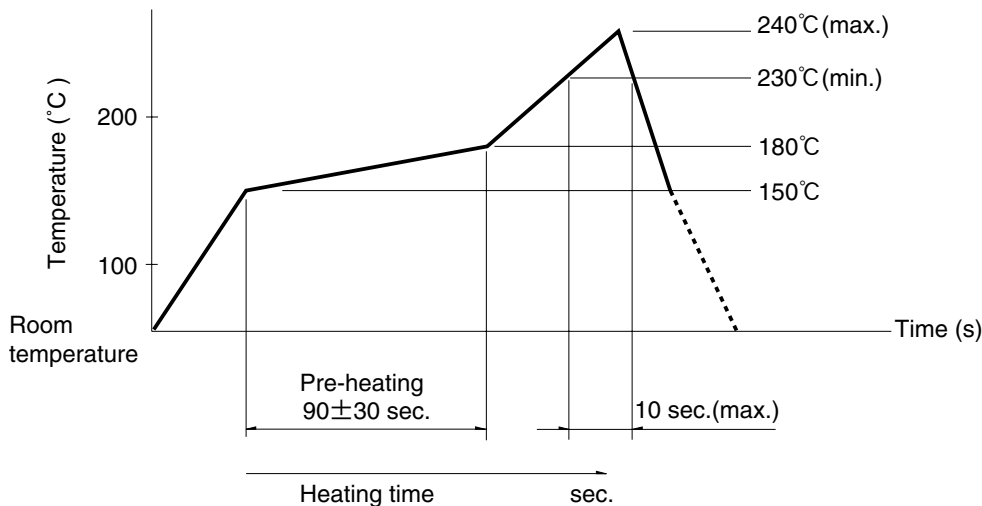
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## Soldering Conditions

### Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



## Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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